

10 9 8 7 6 5 4 3 2 1

F

F

E

E

D

D

C

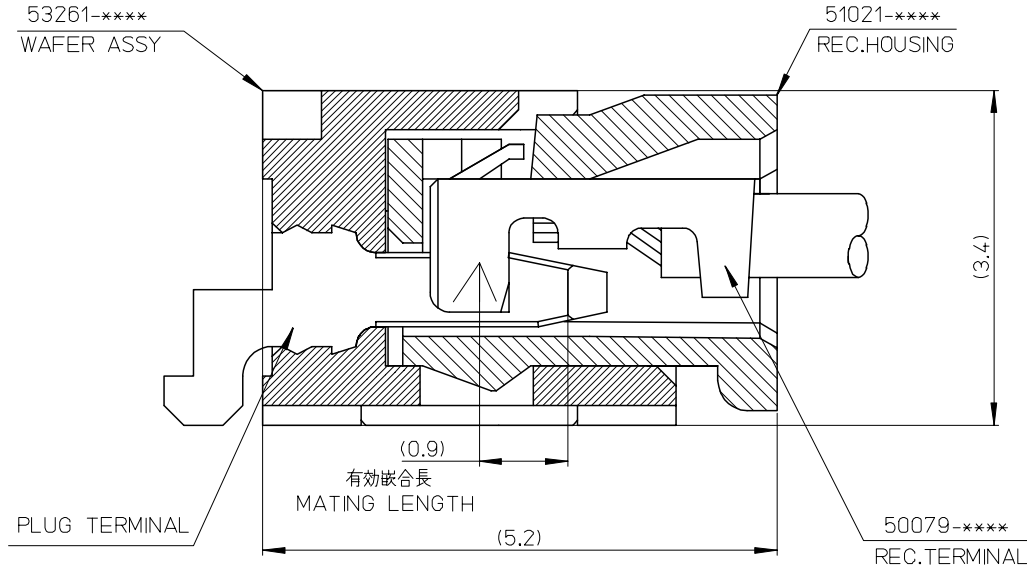
C

B

B

A

A

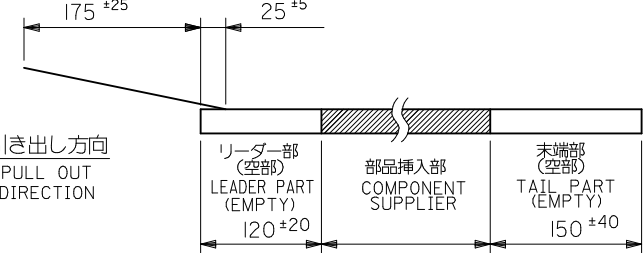


53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: A0YAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION			
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	DOCUMENT NO. SD-51021-002			
	ANGULAR	± --- °	MATERIAL NO. SEE CHART		SHEET NO. 1 OF 1			
0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

注記  
NOTES

- 53261-\*\*-19 の詳細寸法については図面 SD-53261-024 を参照下さい。  
RE DETAILED DIMENSIONS, SEE SD-53261-024
- 梱包数量: 1000個/リール  
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH  
トップテープリーダー部 TOP TAPE LEADER PART  
トップテープ未接着部 TOP TAPE NON-BONDED PART



- 材料 (MATERIAL)  
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)  
トップテープ (TOP TAPE): PET, PE, PEF  
リール (REEL): ポリスチレン (PS) <リサイクル材含む>  
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

△ コネクタ、ハウジング平面部  
CONNECTOR, HOUSING FLAT AREA

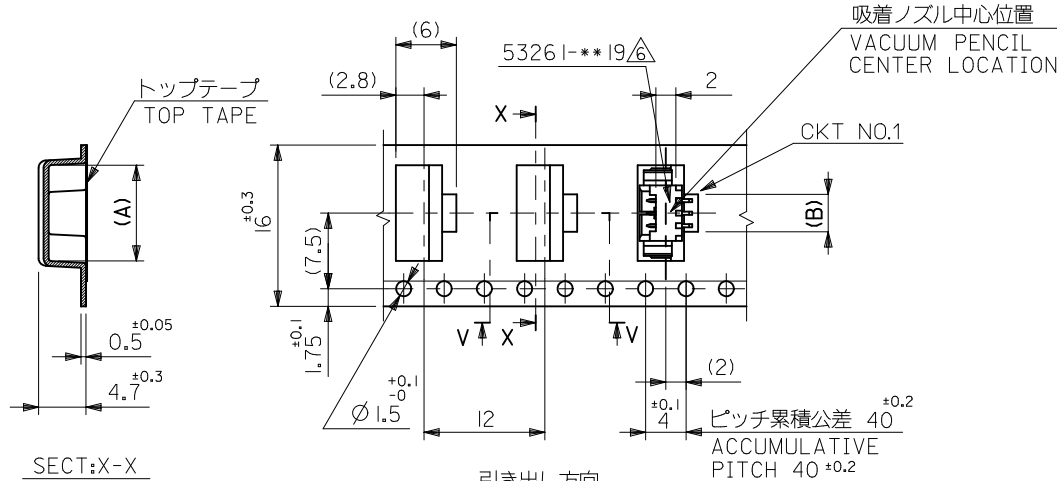
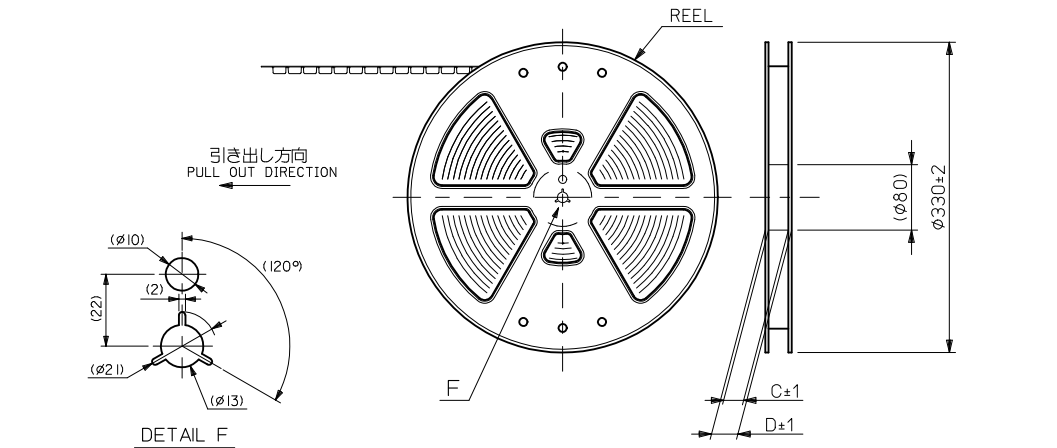
- 本製品は 53261-\*\*-90 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53261-\*\*-90

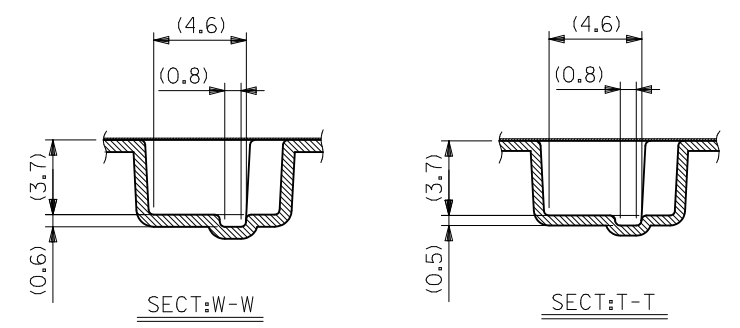
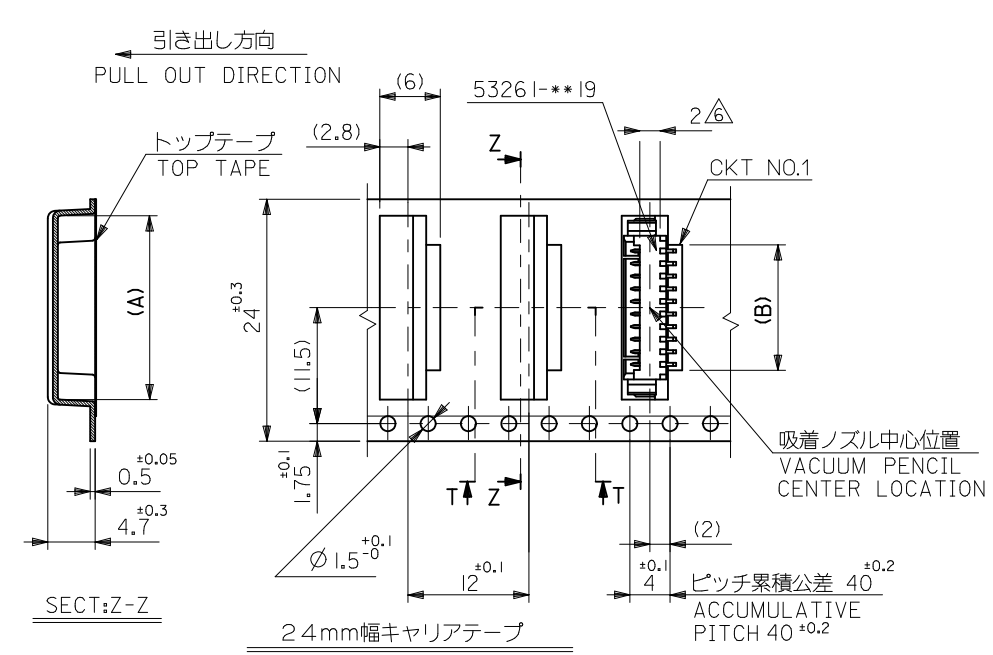
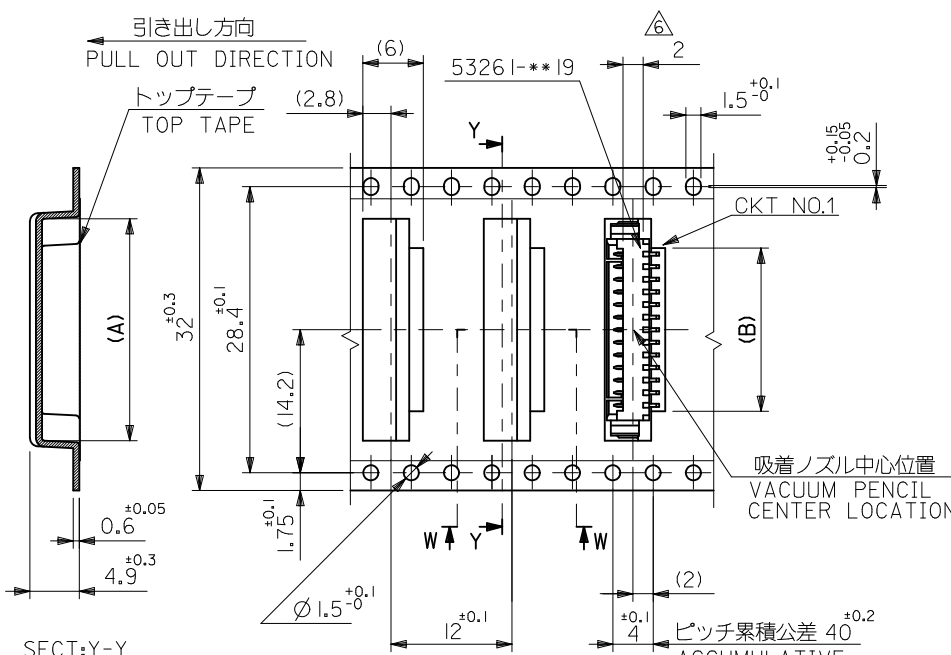
- ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT

- 本製品は乾燥剤入り、ハイバリア梱包仕様である。  
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

16	21.4	17.4	3.7	9.5	53261-0371	3				
			2.45	8.25	53261-0271	2				
キャリアテープ幅 CARRIER TAPE WIDTH					D	C	B	A	EMBOSSD TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.

REVISED	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
EC NO: D	2010/02/17 DRWN: YGOTO CHKD: KASAKAWA APPR:	10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY: H. SHIMABUKUR DATE: '04/02/06 CHECKED BY: K. TOJO DATE: '04/02/06 APPROVED BY: NUKITA DATE: 2010/02/18	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG	MATERIAL NO. SEE TABLE & SHEET 2,3	DOCUMENT NO. SD-53261-023
REV	REV	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

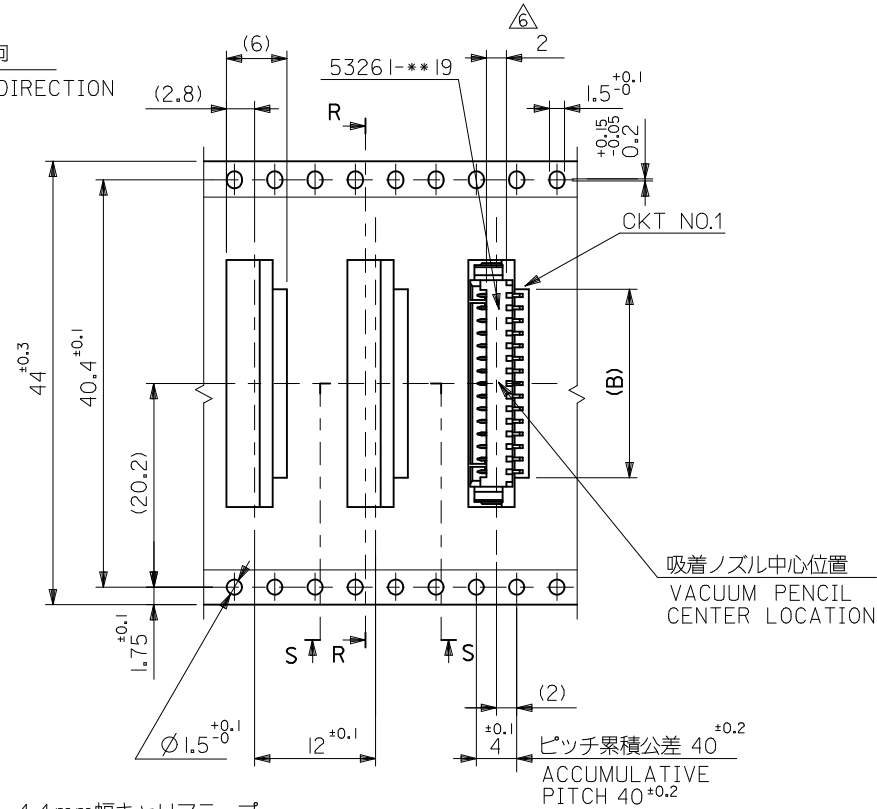
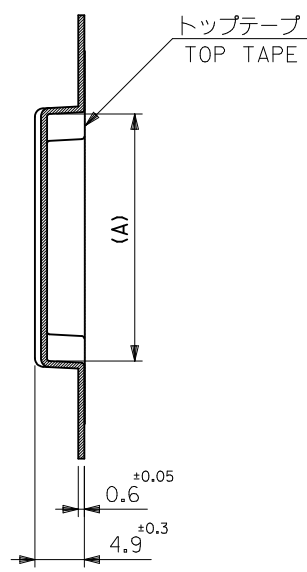




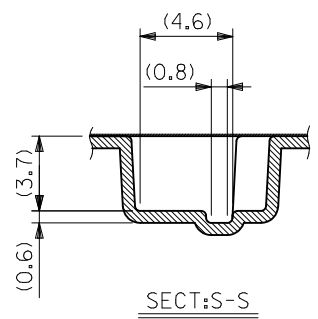
32	37.4	33.4	16.2	22	53261-1371	13	
			14.95	20.75		-1271	12
24	29.4	25.4	13.7	19.5	53261-0471	11	
			12.45	18.25		-1071	10
			11.2	17		-0971	9
			9.95	15.75		-0871	8
			8.7	14.5		-0771	7
			7.45	13.25		-0671	6
			6.2	12		-0571	5
4.95	10.75		4				

MODEL NO.	53261-***71	キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	EMBOSSD TAPE PACKAGE	極数 CKT.
REVISED	2010/02/17	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY			SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
EC NO.	DRWN:YG010 CHKD:KASAKAWA APPR:	10 UNDER ±0.2	DRAWN BY H. SHIMABUKUR	DATE '04/02/06	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG			
		10 OVER 30 UNDER ±0.25	CHECKED BY K. TOJO	DATE '04/02/06	MOLEX INCORPORATED			
		30 OVER ±0.3	APPROVED BY NUKITA	DATE 2010/02/18	DOCUMENT NO. SD-53261-023			
		ANGULAR ±3 °	MATERIAL NO.	SEE TABLE & SHEET 1.3	SHEET NO. 2 OF 3			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

引き出し方向  
PULL OUT DIRECTION



44mm幅キャリアテープ  
44mm WIDTH CARRIER TAPE



44	49.4	45.4	18.7	24.5	53261-1571	15
			17.45	23.25	53261-1471	14
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	EMBOSSD TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.

REVISED	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
EC NO: D	2010/02/17	10 UNDER ±0.2	MM ONLY	---	METRIC	☉ □
DRWN: YGOTO		10 OVER 30 UNDER ±0.25	DRAWN BY DATE			TITLE
CHKD: KASAKAWA		30 OVER ±0.3	H. SHIMABUKUR '04/02/06			1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG
APPR:		ANGULAR ±3 °	CHECKED BY DATE			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	K. TOJO '04/02/06			
			APPROVED BY DATE			
			NUKITA 2010/02/18			
			MATERIAL NO.	SEE TABLE & SHEET 12	MATERIAL NO.	DOCUMENT NO.
					MOLEX INCORPORATED	
					SD-53261-023	SHEET NO.
						3 OF 3

